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By: Dry & D.

Date: 1/16/03

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant

: Albrecht Mayer

Applic. No.

: 09/164,123

Filed

: September 30, 1998

Title

Method for Assembling Integrated Circuits

With Protection Of The Circuits Against Electrostatic Discharge, And Arragement Of

Integrated Circuits With Protection Against

Electrostatic Discharge

Examiner

: Julio J. Maldonado

Group Art Unit: 2823

## AMENDMENT under 37 C.F.R. § 1.116

Hon. Commissioner of Patents and Trademarks, Washington, D. C. 20231

Sir:

Responsive to the final Office action dated November 6, 2002 kindly amend the above-identified application as follows:

## In the Claims:

Claim 1 (twice-amended). A method for producing an electrical connection between integrated circuit chips, which comprises: